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APPLICATION NO.	FI	LING DATE	FIRST NAMED INVENTOR	ATTORNEY DOCKET NO.	CONFIRMATION NO.
10/016,142	12/17/2001		Hirotoshi Kubo	492322002600	4143
25227	7590	03/29/2004		EXAMINER	
MORRISO	N & FOE	ERSTER LLP	LATTIN, CHRISTOPHER W		
1650 TYSO1 SUITE 300	NS BOUL	EVARD	ART UNIT	PAPER NUMBER	
MCLEAN,	VA 2210	2	2812		

Please find below and/or attached an Office communication concerning this application or proceeding.

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	Application No.	Applicant(s)
Office Action Common and	10/016,142	KUBO ET AL.
Office Action Summary	Examiner	Art Unit
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The MAILING DATE of this communication app Period for Reply	pears on the cover sheet with the	correspondence address
A SHORTENED STATUTORY PERIOD FOR REPL THE MAILING DATE OF THIS COMMUNICATION. - Extensions of time may be available under the provisions of 37 CFR 1.1 after SIX (6) MONTHS from the mailing date of this communication. - If the period for reply specified above is less than thirty (30) days, a repl - If NO period for reply is specified above, the maximum statutory period of the period for reply within the set or extended period for reply will, by statute any reply received by the Office later than three months after the mailing earned patent term adjustment. See 37 CFR 1.704(b).	36(a). In no event, however, may a reply be to within the statutory minimum of thirty (30) downwill apply and will expire SIX (6) MONTHS from a cause the application to become ABANDON	imely filed ays will be considered timely. m the mailing date of this communication. IED (35 U.S.C. § 133).
Status		
 1) ⊠ Responsive to communication(s) filed on 13 Journal 2a) ⊠ This action is FINAL. 2b) □ This 3) □ Since this application is in condition for allowance closed in accordance with the practice under Expensive to communication(s) filed on 13 Journal 25 and 15 Journal 25 □ This 2b □ This	s action is non-final. nce except for formal matters, p	
Disposition of Claims		
 4) Claim(s) 1-17 is/are pending in the application 4a) Of the above claim(s) 1-8 is/are withdrawn 5) Claim(s) is/are allowed. 6) Claim(s) 9-17 is/are rejected. 7) Claim(s) is/are objected to. 8) Claim(s) are subject to restriction and/or 	from consideration.	
Application Papers		
9) The specification is objected to by the Examine 10) The drawing(s) filed on is/are: a) accomplicant may not request that any objection to the Replacement drawing sheet(s) including the correct 11) The oath or declaration is objected to by the Examine 10.	cepted or b) objected to by the drawing(s) be held in abeyance. So tion is required if the drawing(s) is o	ee 37 CFR 1.85(a). bjected to. See 37 CFR 1.121(d).
Priority under 35 U.S.C. § 119		
12) Acknowledgment is made of a claim for foreign a) All b) Some * c) None of: 1. Certified copies of the priority document 2. Certified copies of the priority document 3. Copies of the certified copies of the priority application from the International Burea * See the attached detailed Office action for a list	ts have been received. Its have been received in Application of the contract	ntion No ved in this National Stage
Attachment(s)		
1) Notice of References Cited (PTO-892) 2) Notice of Draftsperson's Patent Drawing Review (PTO-948) 3) Information Disclosure Statement(s) (PTO-1449 or PTO/SB/08) Paper No(s)/Mail Date	4) Interview Summar Paper No(s)/Mail I 5) Notice of Informal 6) Other:	• •

DETAILED ACTION

Claim Rejections - 35 USC § 102

The following is a quotation of the appropriate paragraphs of 35 U.S.C. 102 that form the basis for the rejections under this section made in this Office action:

A person shall be entitled to a patent unless -

(b) the invention was patented or described in a printed publication in this or a foreign country or in public use or on sale in this country, more than one year prior to the date of application for patent in the United States.

Claims 9-12 are rejected under 35 U.S.C. 102(b) as being anticipated by Nakashima (5,811,871, cited by applicant).

Nakashima et al. teach a method for manufacturing a semiconductor device comprising the steps of: forming a base region 30 of a first conducting type on a surface of a collector layer 4 of a second conducting type; forming a polysilicon base electrode layer 15 on a surface of the base region and forming an insulating film 31 on a surface of the base electrode layer; forming a trench 32 (see Fig. 41), which does not reach the collector layer, in the base region by creating an opening at a part of the base electrode layer and the insulating film and forming a sidewall 35 on an inside wall of the trench, thus forming a γ-shaped trench; forming a polysilicon layer 37 containing impurities for emitter diffusion inside the trench, forming an emitter region 38 by diffusing the impurities of the polysilicon layer; and forming a through hole on the insulating film so as to form a base electrode 41 which comes into contact with the base electrode layer 15 and at the same time forming an emitter electrode 41 which comes into contact with the polysilicon layer. See Figures 1-4, 30-43.

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Claims 13 and 14 are rejected under 35 U.S.C. 102(b) as being anticipated by Yoshihara (5,789,285).

Yoshihara teaches a method for manufacturing a semiconductor device comprising the steps of: preparing a collector layer 63 of a first conducting type; forming a base electrode layer 43 made of polysilicon containing impurities of a second conducting type on a surface of the collector layer and forming an insulating film 54 on the surface of the base electrode layer; forming a trench 55 in the collector layer by creating an opening at a part of the base electrode layer and the insulating film and doping impurities of the second conducting type so that a doped region 84 is formed around the trench and in the base electrode layer; forming a sidewall 56 on an inside wall of the trench; forming a polysilicon layer 86 containing impurities for emitter diffusion inside the trench; diffusing the impurities of the second conducting type of the doped region for forming a base region 94 and, at the same time, diffusing the impurities of the polysilicon layer for forming an emitter region 93, and forming a through hole on the insulating film and forming a base electrode 51 which comes into contact with the base electrode layer and, at the same time, forming an emitter electrode 51 which comes into contact with the polysilicon layer, wherein the trench is formed as a γshaped trench. See Figures 2 and 3A-3K.

Response to Arguments

Applicant's arguments filed 12/29/2003 have been fully considered but they are not persuasive. Applicant argues that the base region was not formed prior to forming

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the base electrode. However, a base P- doped region 42 was implanted prior to forming the base electrode. Although the base region may not have been completed, region 42 represents the doped the surface of the base region as required by the language of claim 9. Therefore, the rejection with respect to this element was proper.

The argument that the trench formed in Nakashima is not gamma shaped also fails. Layer 35 is etched so as to leave a gamma shaped trench. Therefore, the rejection with respect to this element was proper.

Applicant further argues that Yoshihara teaches that polysilicon layer 43 is doped before the formation of the trench. As pointed out in the rejection, Yoshihara teaches doping which results in the formation of region 84. The fact that the electrode may be doped twice is of no matter as applicant claims that the base electrode is doped with impurities of a second conductive type. Therefore, the rejection with respect to this element was proper.

The argument that the trench formed in Yoshihara is not gamma shaped also fails. Layer 56 is etched so as to leave a gamma shaped trench. Therefore, the rejection with respect to this element was proper.

Conclusion

Any inquiry concerning this communication or earlier communications from the examiner should be directed to Christopher Lattin whose telephone number is (571) 272-1673. The examiner can normally be reached Monday through Friday from 8:00 A.M. to 5:00 P.M.

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If attempts to reach the examiner by telephone are unsuccessful, the examiner's supervisor, John Niebling, can be reached at (571) 272-1679. The fax number for this Group is (703) 872-9306.

Any inquiry of a general nature or relating to the status of this application or proceeding should be directed to the Group receptionist whose telephone number is (703) 308-0956.

CWL 2 ____ March 25, 2004 Supervisory Patent Examiner Technology Center 2800